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Abstract of the Disclosure

A method for producing printed circuit boards, which comprises the following method steps:

- (A) coating both sides of a through-plated copper laminate using a negative electrodeposition-resist;
 - (B) structuring the resist coating by imagewise exposure to light, the through-platings being covered by a mask, and then developing;
 - (C) applying a metal resist by electrodeposition;
 - (D) removing the crosslinked negative photoresist remaining on the laminate;
 - (E) removing the bare copper by means of an etching solution; and
 - (F) removing the metal resist by means of a stripper solution,
- yields through-platings having reduced annular rings.



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